Chip Type, Higher Capacitance

Fre OMP









- Higher Capacitance, Low ESR, High ripple current.
- Load life of 2000 hours at 105°C.
- SMD type: Lead free reflow soldering condition at 260°C peak correspondence.
- Adapted to the RoHS directive (2002/95/EC).



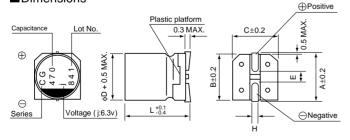


■Specifications

Item	Performance Characteristics							
Category Temperature Range	−55 to +105°C							
Rated Voltage Range	2.5 to 16V							
Rated Capacitance Range	47 to 3300µF							
Capacitance Tolerance	±20% at 120Hz, 20°C							
Tangent of loss angle (tan δ)	Less than or equal to the specified value at 120Hz, 20°C							
ESR (* 1)	Less than or equal to the specified value at 100kHz, 20°C							
Leakage Current (* 2)	Less than or equal to the specified value. After 2 minutes' app	lication of rated voltage	at 20°C					
Temperature Characteristics (Max.Impedance Ratio)	$Z+105^{\circ}C / Z+20^{\circ}C \le 1.25$ (100kHz) $Z-55^{\circ}C / Z+20^{\circ}C \le 1.25$							
Endurance	The specifications listed at right shall be met when the capacitors are restored to 20°C after the rated voltage is applied for 2000 hours at 105°C.	Capacitance change tan δ ESR (* 1) Leakage current (* 2)	Within ± 20% of the initial value (* 3) 150% or less of the initial specified value 150% or less of the initial specified value Less than or equal to the initial specified value					
Damp Heat (Steady State)	The specifications listed at right shall be met when the capacitors are restored to 20°C after the rated voltage is applied for 1000 hours at 60°C, 90% RH.	Capacitance change $\tan \delta$ ESR ($*$ 1) Leakage current ($*$ 2)	Within ± 20% of the initial value (** 3) 150% or less of the initial specified value 150% or less of the initial specified value Less than or equal to the initial specified value					
Resistance to Soldering Heat	After soldering the capacitor under the soldering conditions prescribed here, the capacitor shall meet the specifications listed at right, provided that it's temperature profile is measured at the capacitor top and the terminal. Pre-heating shall be done at 150 to 200°C and for 60 to 180 sec. The duration for over +230°C temperature at capacitor surface shall not exceed 60 seconds. In the case of peak temp, less than 250°C, reflow soldering shall be two times maximum. In the case of peak temp, less than 260°C, reflow soldering shall be once. Measurement for solder temperature profile shall be made at the capacitor top and the terminal.	Capacitance change tan δ ESR (* 1) Leakage current (* 2)	Within ± 10% of the initial value (** 3) 130% or less of the initial specified value 130% or less of the initial specified value Less than or equal to the initial specified value					
Marking	Navy blue print on the case top							

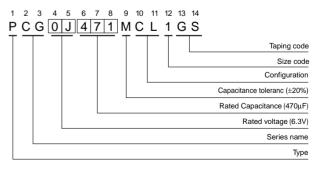
- * 1 ESR should be measured at both of the terminal ends closest where the terminals protrude through the plastic platform.
- * 3 Initial value: The value before test of examination of resistance to soldering.

Dimensions



						(mm)
Size	φ5×6L	6×6 L $ \phi 6.3 \times 6$ L $ \phi 8 \times 7$ L $ \phi 10 \times 8$ L $ \phi 10 \times 9$		φ10 × 10L	φ10 × 12.7L	
φD	5.0	6.3	8.0	10.0	10.0	10.0
L	5.9	5.9 5.9 6.9 7.9 9.9		9.9	12.6	
Α	6.0	7.3	9.0	11.0	11.0	11.0
В	5.3	6.6	8.3	10.3	10.3	10.3
С	5.3	6.6	8.3	10.3	10.3	10.3
E	1.6	2.1	3.2	4.6	4.6	4.6
Н	0.5 to 0.8	0.5 to 0.8	0.8 to 1.1	0.8 to 1.1	0.8 to 1.1	0.8 to 1.1

Type numbering system (Example : $6.3V 470 \mu F$)



Voltage

V	2.5	4	4 6.3		16
Code	е	g	j	Α	С



■Standard ratings

Rated Voltage (V)(code)	Surge Voltage (V)	Rated Capacitance (µF)	Case Size φD × L (mm)	tan δ	Leakage Current (μΑ)	ESR (mΩ) (at 100kHz 20°C)	Rated ripple (mArms)	Part Number
2.5 (0E)	2.8	220	5×6	0.12	110	30	2100	PCG0E221MCL1GS
		470	6.3×6	0.12	235	20	2900	PCG0E471MCL1GS
		560	6.3×6	0.12	280	20	3000	PCG0E561MCL1GS
		820	8×7	0.12	410	20	3300	PCG0E821MCL1GS
		1500	10 × 8	0.12	750	17	4100	PCG0E152MCL1GS
		2700	10 × 10	0.12	1350	12	4700	PCG0E272MCL1GS
		3300	10×12.7	0.12	1650	10	5500	PCG0E332MCL1GS
		180	5×6	0.12	144	32	1900	PCG0G181MCL1GS
		390	6.3×6	0.12	312	22	2700	PCG0G391MCL1GS
4	4.6	680	8 × 7	0.12	544	21	3200	PCG0G681MCL1GS
(0G)	4.0	1200	10 × 8	0.12	960	17	4000	PCG0G122MCL1GS
		2200	10 × 10	0.12	1760	13	4600	PCG0G222MCL1GS
		2700	10×12.7	0.12	2160	11	5300	PCG0G272MCL1GS
	7.2	150	5×6	0.12	189	33	1800	PCG0J151MCL1GS
		270	6.3×6	0.12	340	23	2600	PCG0J271MCL1GS
		330	6.3×6	0.12	416	23	2700	PCG0J331MCL1GS
6.3 (0J)		470	8 × 7	0.12	592	22	3100	PCG0J471MCL1GS
, ,		1000	10 × 8	0.12	1260	18	3800	PCG0J102MCL1GS
		1800	10 × 10	0.12	2268	14	4400	PCG0J182MCL1GS
		2200	10×12.7	0.12	2772	12	5000	PCG0J222MCL1GS
	11.5	82	5×6	0.12	164	35	1700	PCG1A820MCL1GS
		150	6.3×6	0.12	300	25	2500	PCG1A151MCL1GS
10		330	8 × 7	0.12	660	23	3100	PCG1A331MCL1GS
(1A)		560	10 × 8	0.12	1120	20	3600	PCG1A561MCL1GS
		820	10 × 10	0.12	1640	15	4300	PCG1A821MCL1GS
		1000	10×12.7	0.12	2000	13	4800	PCG1A102MCL1GS
16	18.4	47	5×6	0.12	150	40	1500	PCG1C470MCL1GS
		82	6.3×6	0.12	262	30	2300	PCG1C820MCL1GS
		150	8×7	0.12	480	28	2800	PCG1C151MCL1GS
(1C)		270	10×8	0.12	864	25	3300	PCG1C271MCL1GS
		470	10×10	0.12	1504	20	3700	PCG1C471MCL1GS
		680	10 × 12.7	0.12	2176	18	4100	PCG1C681MCL1GS

Rated Ripple (mArms) at 105°C 100kHz

[•] Taping specifications are given in page 23.

[•] Recommended land size, soldering by reflow are given in page 18, 19.

• Please refer to page 3 for the minimum order quantity.